

## High Output Current, Rail-to-Rail Input/Output Dual CMOS Operational Amplifier

### ■ GENERAL DESCRIPTION

The NJU77902 is a Rail-to-Rail input and output dual CMOS operational amplifier that features high output current drive.

This device is stable to capacitive load and can charge and discharge capacitance quickly by high output current up to 1000mA. In addition, it is ideal for buffer amplifiers as the output stage can supply a respectable amount of current with minimal headroom from either rail.

### ■ PACKAGE OUTLINE



NJU77902KW2  
(ESON8-W2)

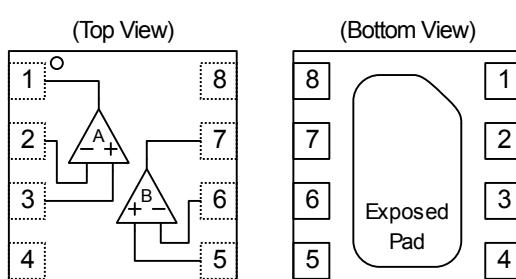
### ■ FEATURES

- Output Peak Current 1000mA (typ.)
- Rail-to-Rail Input/Output
- Wide Operating Voltage 6V to 18V
- Slew Rate 9V/ $\mu$ s (typ.)
- Package ESON8-W2 (3.0mm x 3.0mm)
- Enhanced RF Noise Immunity
- CMOS Process

### ■ APPLICATION

- TFT-LCD panel V<sub>COM</sub> driver
- Instrument Control Voltage Source

### ■ PIN CONFIGURATION



NJU77902KW2

About Exposed Pad

Connect the Exposed Pad on the V<sub>SS</sub>.

### PIN FUNCTION

1. A OUTPUT
2. A-INPUT
3. A +INPUT
4. V<sub>SS</sub>
5. B +INPUT
6. B -INPUT
7. B OUTPUT
8. V<sub>DD</sub>

# NJU77902

## ■ ABSOLUTE MAXIMUM RATINGS (Ta=25°C, unless otherwise noted.)

| PARAMETER                   | SYMBOL           | RATINGS   | UNIT |
|-----------------------------|------------------|---|------|
| Supply Voltage              | V <sub>DD</sub>  | +20   | V    |
| Power Dissipation           | P <sub>D</sub>   | 560(Note1), 750(Note2), 910(Note3), 2500(Note4) | mW   |
| Output Peak Current         | I <sub>OP</sub>  | 1000  | mA   |
| Input Common Mode Voltage   | V <sub>ICM</sub> | V <sub>SS</sub> -0.3 to V <sub>DD</sub> +0.3    | V    |
| Differential Input Voltage  | V <sub>ID</sub>  | 18 (Note5)                                      | V    |
| Operating Temperature Range | T <sub>opr</sub> | -40 to +85                                      | °C   |
| Storage Temperature Range   | T <sub>stg</sub> | -55 to +150                                     | °C   |

(Note1) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 2Layers FR-4)

(Note2) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 2Layers FR-4, with Exposed Pad)

(Note3) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 4Layers FR-4)

(Note4) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 4Layers FR-4, with Exposed Pad)

(For 4Layers: Applying 99.5×99.5mm inner Cu area and a thermal via hole to a board based on JEDEC standard JESD51-5)

(Note5) For supply voltage less than 18V, the absolute maximum rating is equal to the supply voltage.

## ■ RECOMMENDED OPERATING CONDITION (Ta=25°C)

| PARAMETER      | SYMBOL          | RATING      | UNIT |
|----------------|-----------------|-------------|------|
| Supply Voltage | V <sub>DD</sub> | 6.0 to 18.0 | V    |

## ■ ELECTRICAL CHARACTERISTICS

(V<sub>DD</sub>=15V, V<sub>SS</sub>=0V, V<sub>IC</sub>=7.5V, R<sub>L</sub>=10kΩ to V<sub>DD</sub>/2, Ta=25°C, unless otherwise noted.)

| PARAMETER                          | SYMBOL           | TEST CONDITION   | MIN. | TYP. | MAX. | UNIT   |
|------------------------------------|------------------|--|------|------|------|--------|
| <b>• DC CHARACTERISTICS</b>        |                  |  |      |      |      |        |
| Maximum Output Voltage             | V <sub>OH1</sub> | R <sub>L</sub> = 10kΩ  | 14.8 | 14.9 | -    | V      |
|                                    | V <sub>OH2</sub> | I <sub>source</sub> = 200mA  | 14.2 | 14.5 | -    | V      |
|                                    | V <sub>OL1</sub> | R <sub>L</sub> = 10kΩ  | -    | 0.1  | 0.2  | V      |
|                                    | V <sub>OL2</sub> | I <sub>sink</sub> = 200mA  | -    | 0.5  | 0.8  | V      |
| Input Offset Voltage               | V <sub>IO</sub>  | R <sub>S</sub> = 50Ω   | -    | 1    | 10   | mV     |
| Input Bias Current                 | I <sub>B</sub>   |  | -    | 1    | -    | pA     |
| Input Offset Current               | I <sub>IO</sub>  |  | -    | 1    | -    | pA     |
| Large Signal Voltage Gain          | A <sub>V</sub>   | V <sub>O</sub> = 13V/2V, R <sub>L</sub> =10kΩ  | 65   | 90   | -    | dB     |
| Common Mode Rejection Ratio        | CMR              | V <sub>IC</sub> = 0V → 7.5V<br>V <sub>IC</sub> = 7.5V → 15V                                | 50   | 75   | -    | dB     |
| Supply Voltage Rejection Ratio     | SVR              | V <sub>DD</sub> = 6V → 18V   | 60   | 75   | -    | dB     |
| Input Common Mode Voltage Range    | V <sub>ICM</sub> | CMR ≥ 50dB   | 0    | -    | 15   | V      |
| Operating Current                  | I <sub>DD</sub>  | No Signal, R <sub>L</sub> = open   | -    | 7.0  | 9.0  | mA     |
| <b>• AC CHARACTERISTICS</b>        |                  |  |      |      |      |        |
| Unity Gain Frequency               | f <sub>t</sub>   | C <sub>L</sub> = 10pF  | -    | 3    | -    | MHz    |
| Phase Margin                       | Φ <sub>M</sub>   | C <sub>L</sub> = 10pF  | -    | 50   | -    | deg    |
| Equivalent Input Noise Voltage     | V <sub>NI</sub>  | f = 1kHz, R <sub>S</sub> = 100Ω  | -    | 80   | -    | nV/√Hz |
| Total Harmonic Distortion+Noise    | THD+N            | G <sub>V</sub> = 6dB, C <sub>L</sub> = 10pF, f <sub>in</sub> = 1kHz, P <sub>O</sub> = 0.1W | -    | 0.02 | -    | %      |
| Output Power                       | P <sub>O</sub>   | f <sub>in</sub> =1kHz, C <sub>L</sub> =10pF, THD≤5%  | -    | 3    | -    | mW     |
| Channel Separation                 | CS               | f = 1kHz   | -    | 120  | -    | dB     |
| <b>• TRANSIENT CHARACTERISTICS</b> |                  |  |      |      |      |        |
| Output Peak Current                | I <sub>OP</sub>  | (Note6)  | -    | 1000 | -    | mA     |
| Slew Rate                          | SR               | G <sub>V</sub> = 0dB, C <sub>L</sub> = 10pF, Vin = 4Vpp, (Note7)                           | 5    | 9    | -    | V/μs   |

(Note6) Output peak current is defined by the lower value of the output source current or output sink current.

(Note7) Slew rate is defined by the lower value of the rise or fall.

## ■ Application Notes

### • Package Power, Power Dissipation and Output Power

IC is heated by own operation and possibly gets damage when the junction power exceeds the acceptable value called Power Dissipation  $P_D$ . The dependence of the NJU77902  $P_D$  on ambient temperature is shown in Fig 1. The plots are depended on following two points. The first is  $P_D$  on ambient temperature 25 °C, which is the maximum power dissipation. And the second is 0W, which means that the IC cannot radiate any more. The second point derives from the relation that maximum junction temperature  $T_{j\max}$  is the same as storage temperature  $T_{stg}$ . Fig.1 is drawn by connecting those points and by the definition that the  $P_D$  lower than 25 °C is constant. Therefore, the  $P_D$  is shown following formula as a function of the ambient temperature between those points.

$$\text{Dissipation Power } P_D = \frac{T_{j\max} - T_a}{\theta_{ja}} \text{ [W]} \quad (\text{Ta} = 25^\circ\text{C} \text{ to Ta} = 150^\circ\text{C})$$

Where,  $\theta_{ja}$  is heat thermal resistance which depends on parameters such as package material, frame material and so on. Therefore,  $P_D$  is different in each package.

While, the actual measurement of dissipation power on NJU77902 is obtained using following equation.

$$(\text{Actual Dissipation Power}) = (\text{Supply Voltage } V_{DD}) \times (\text{Supply Current } I_{DD}) - (\text{Output Power } P_o)$$

The NJU77902 should be operated in lower than  $P_D$  of the actual dissipation power.

To sustain the steady state operation, take account of the Dissipation Power and thermal design.

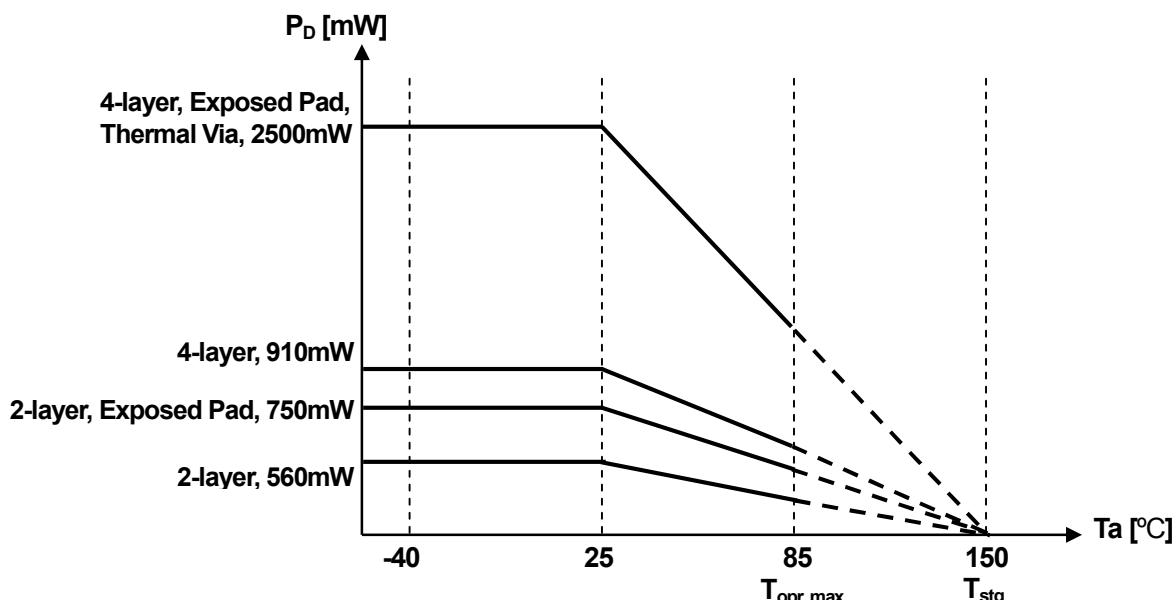
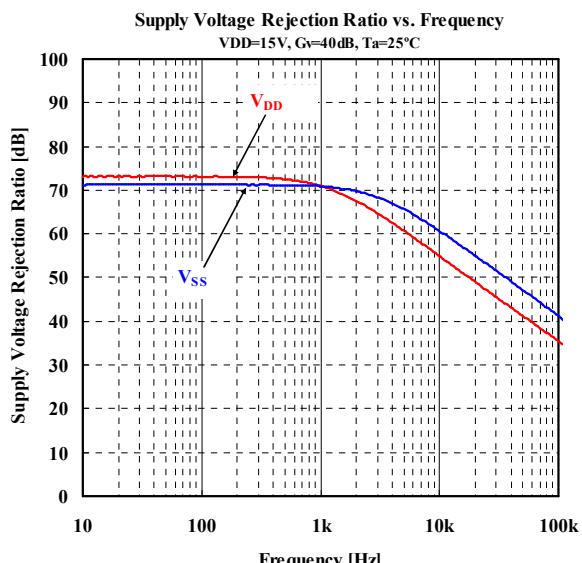
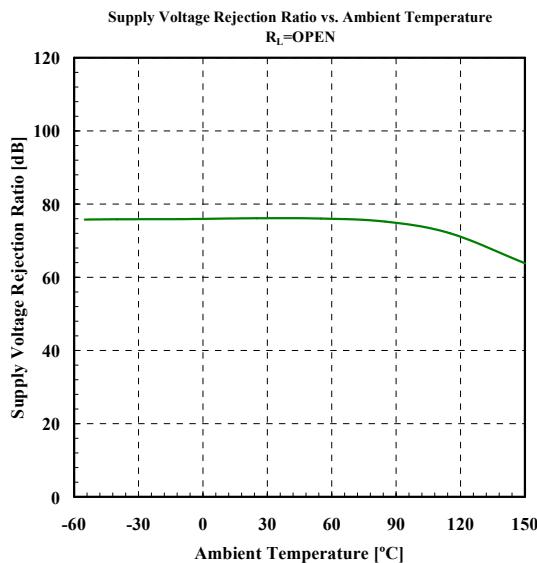
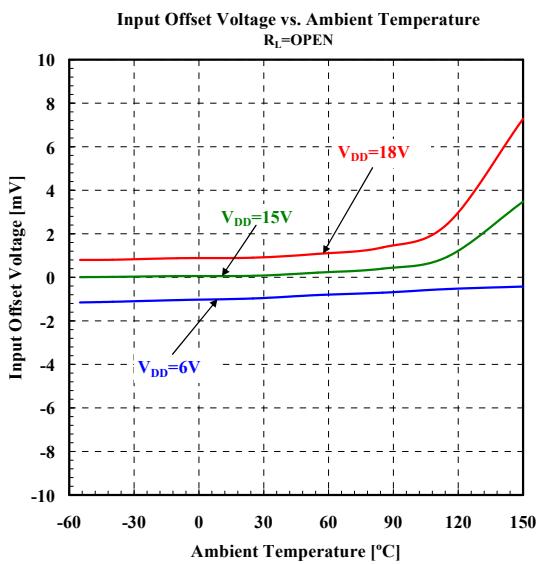
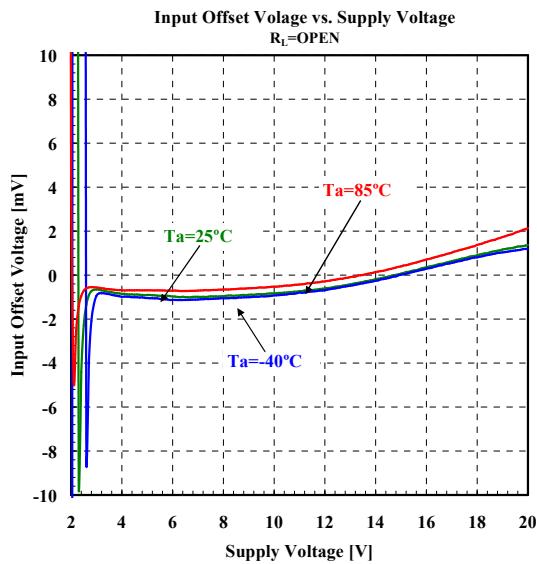
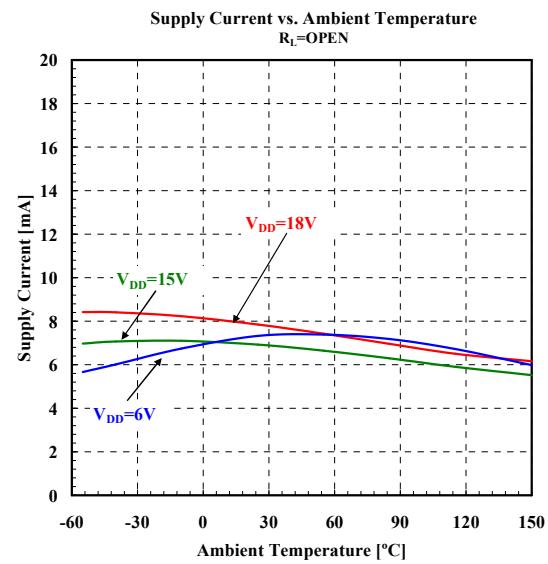
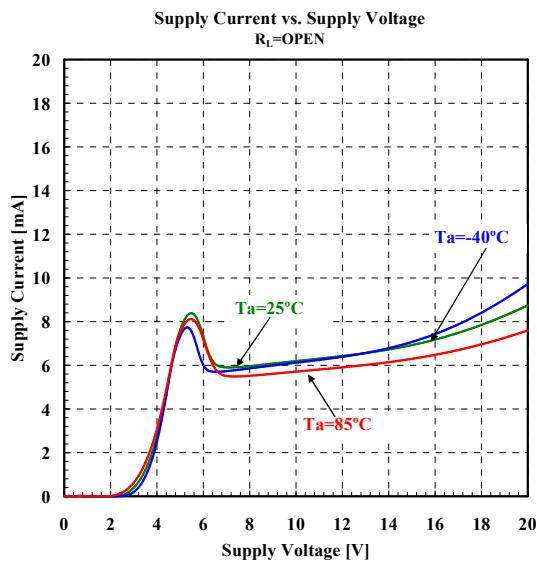
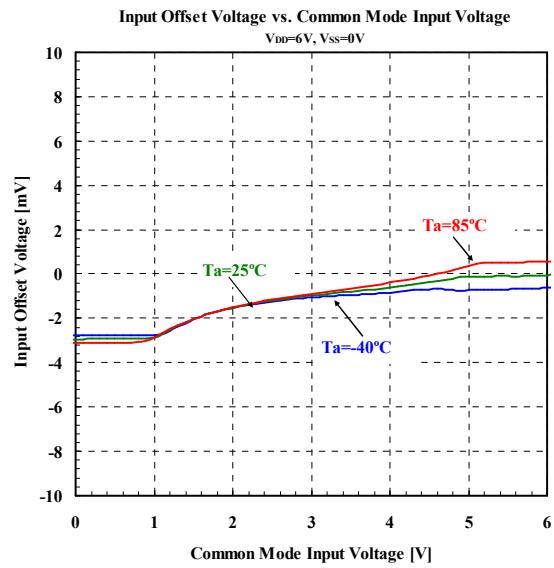
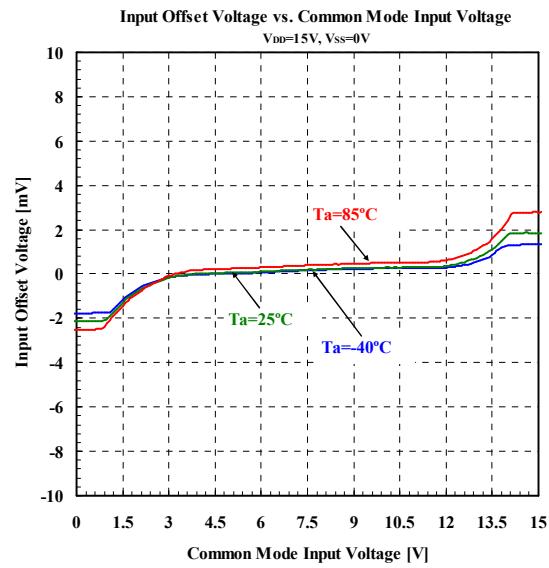
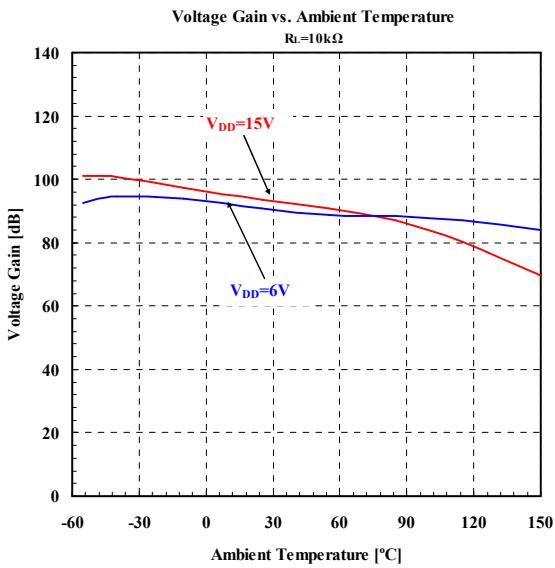
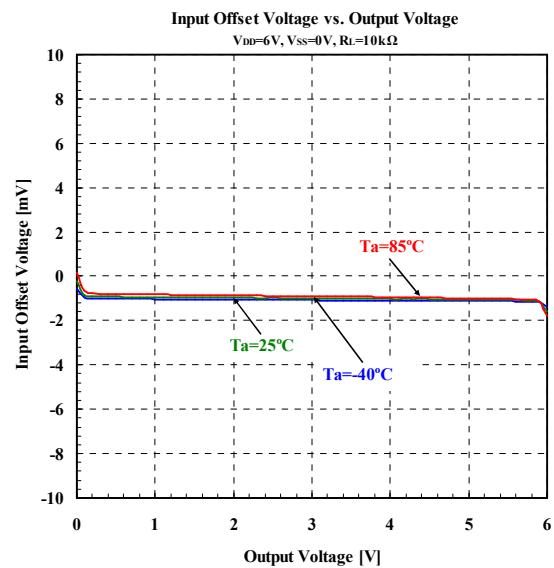
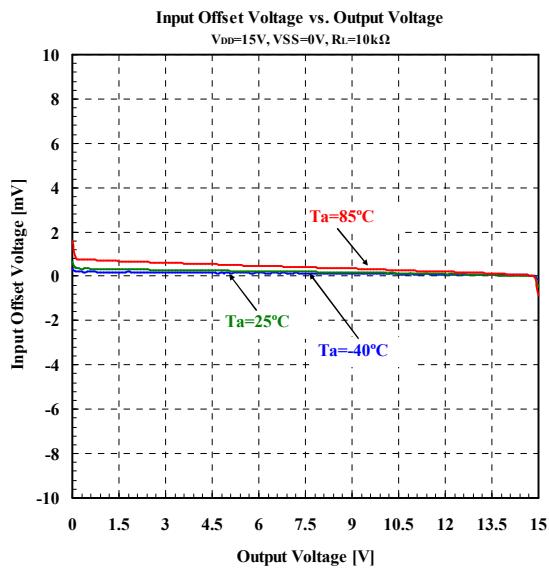


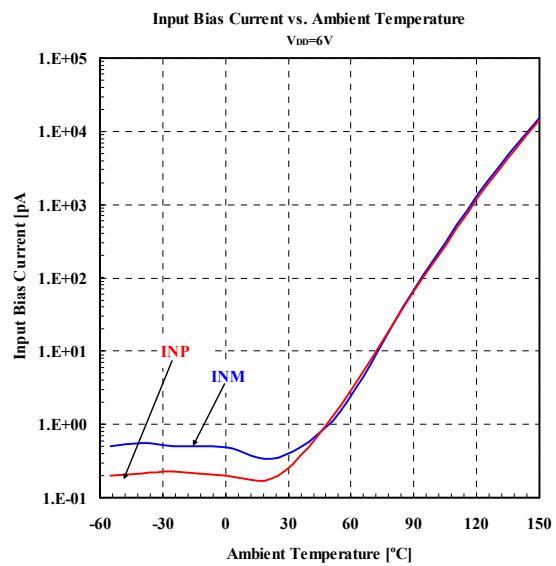
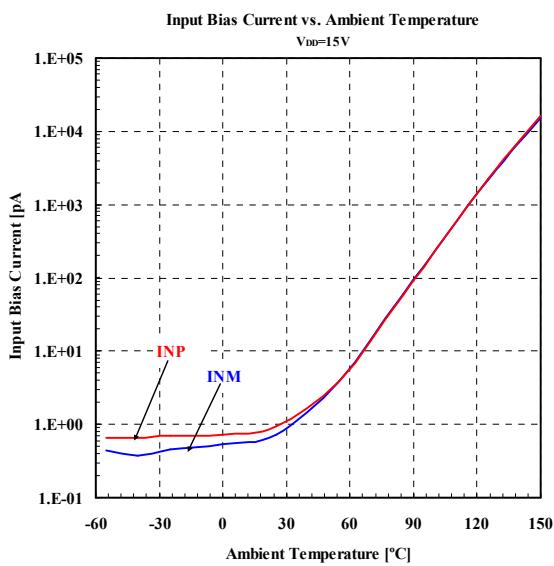
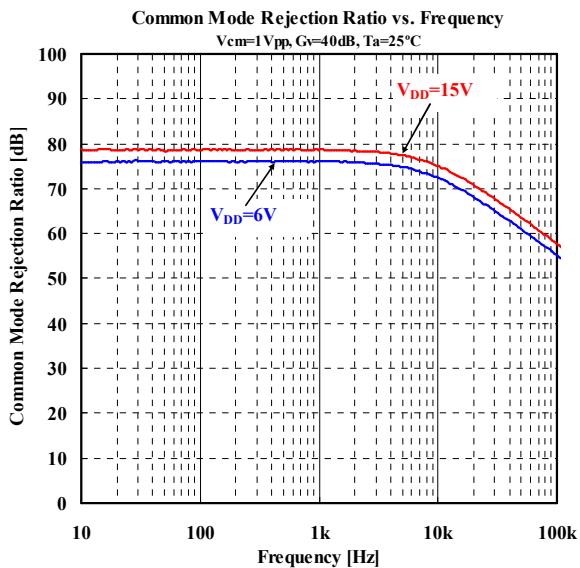
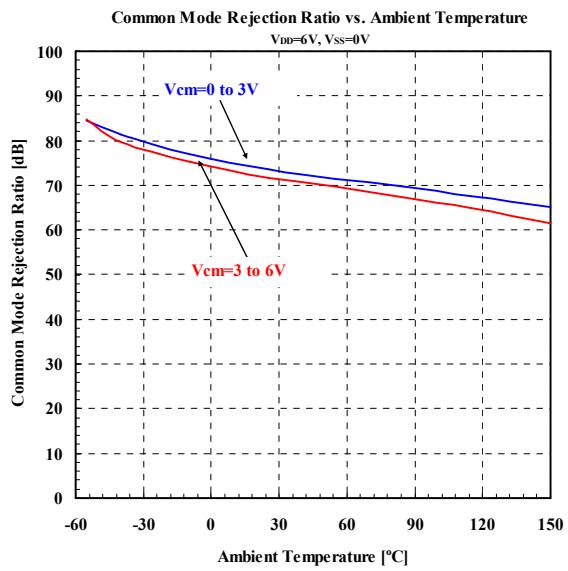
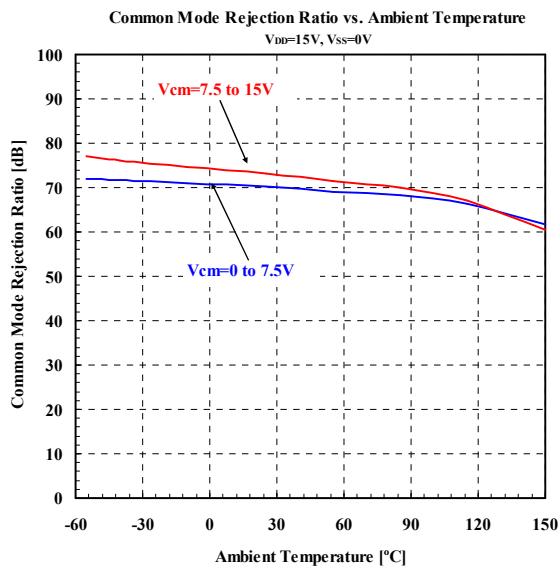
Fig1. Dependence of NJU77902 Power Dissipations on ambient temperature

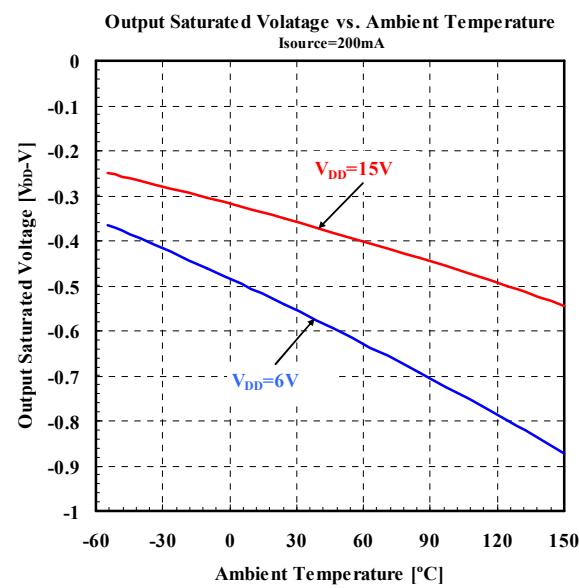
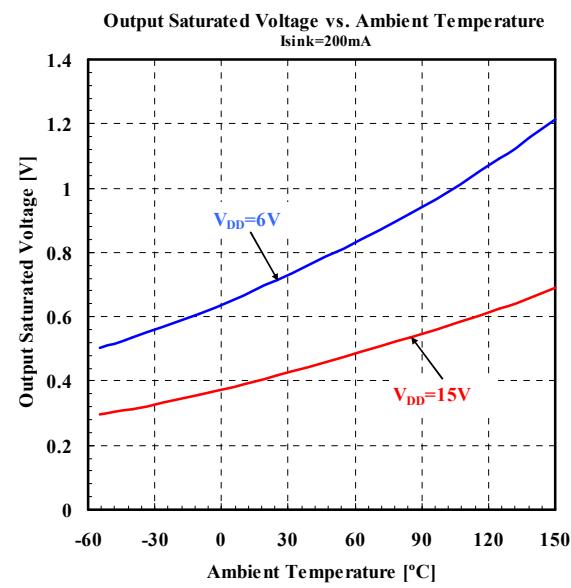
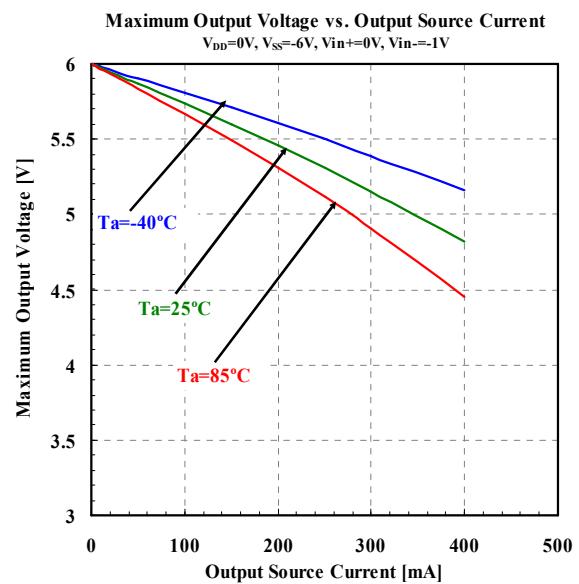
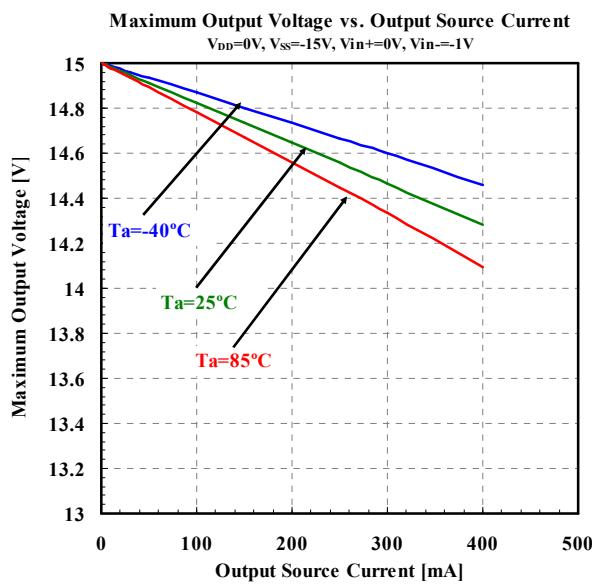
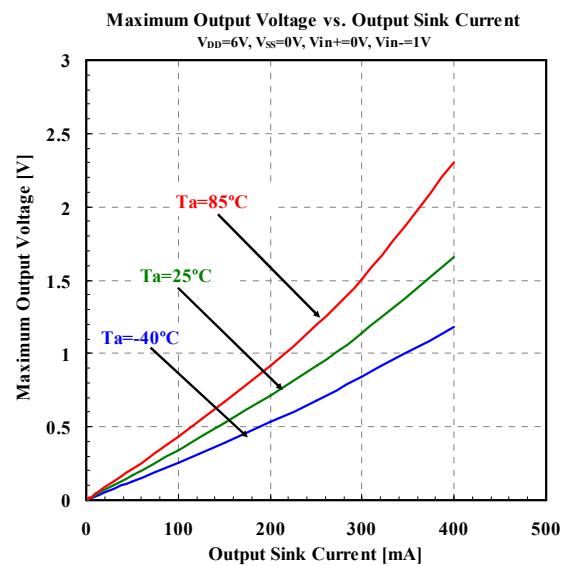
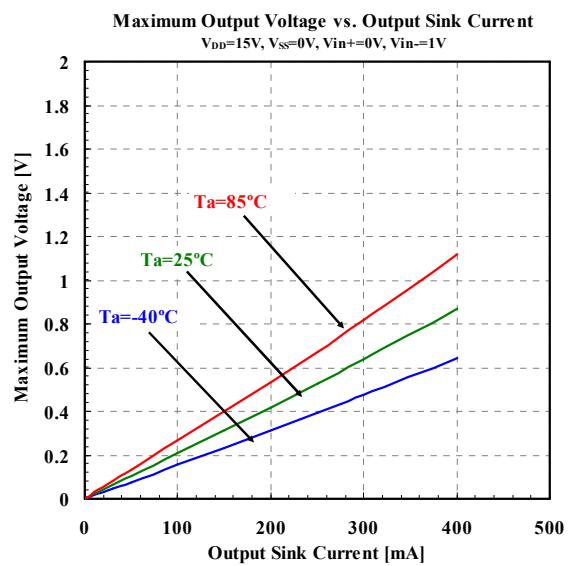
# NJU77902

## ■ TYPICAL CHARACTERISTICS

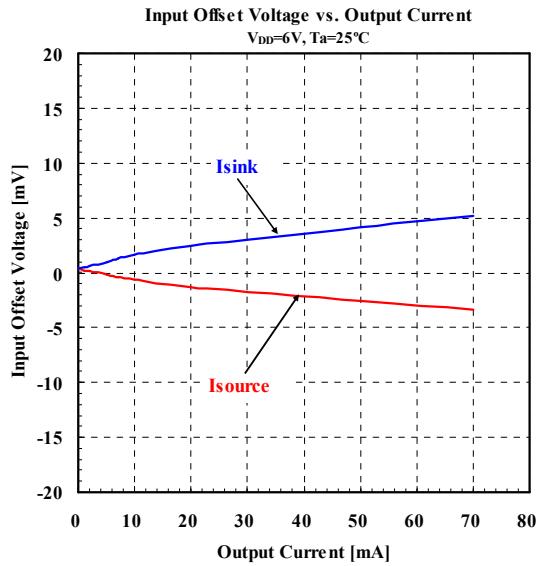
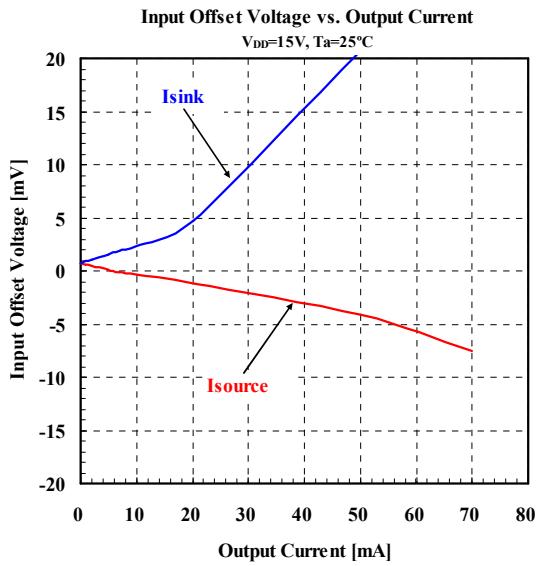
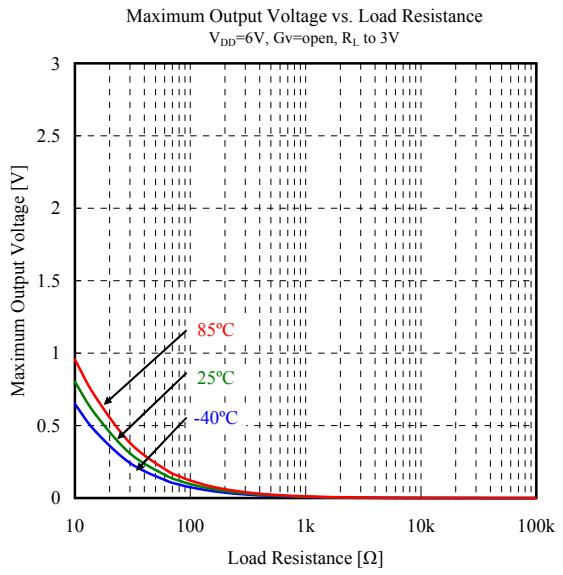
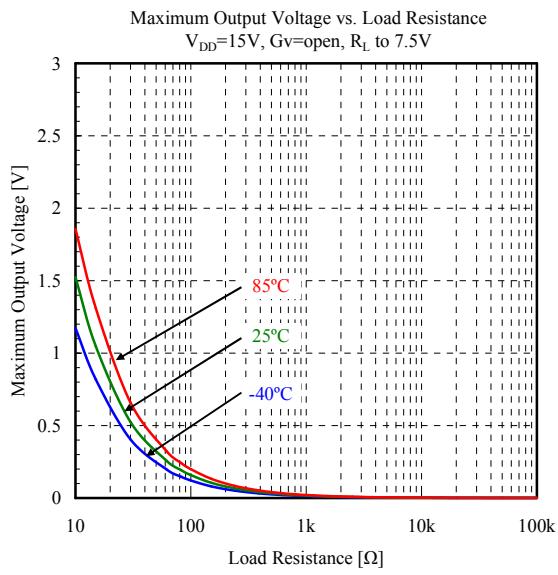
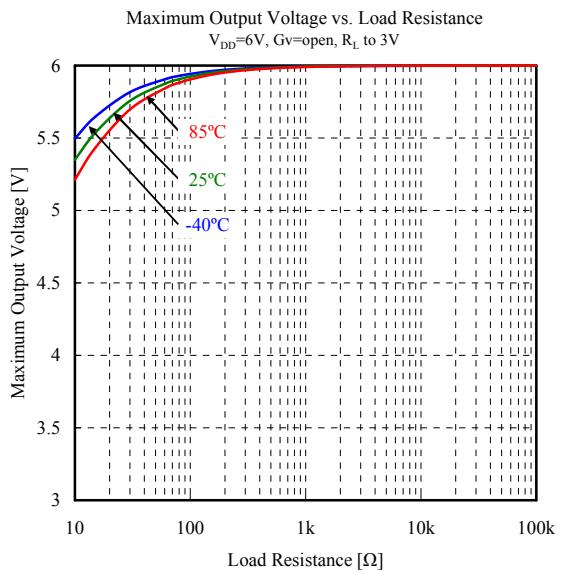
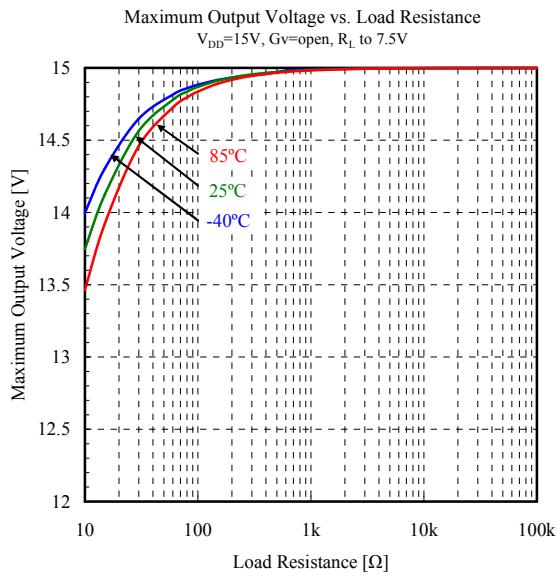


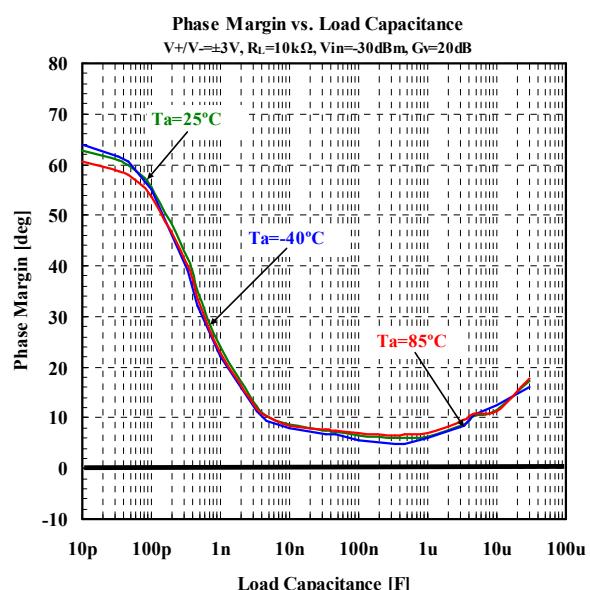
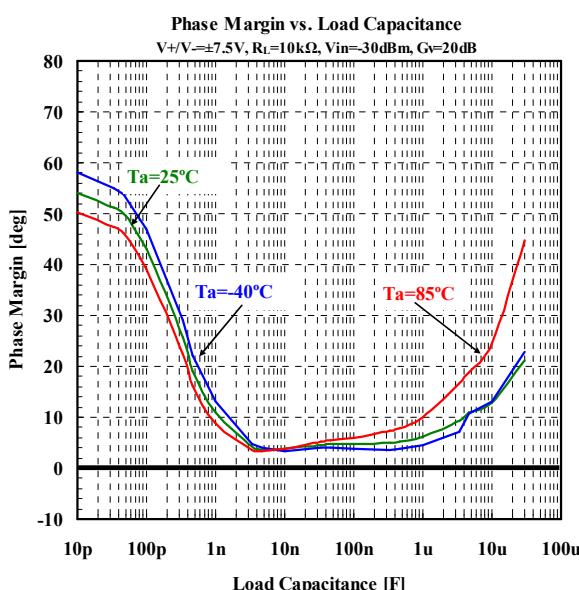
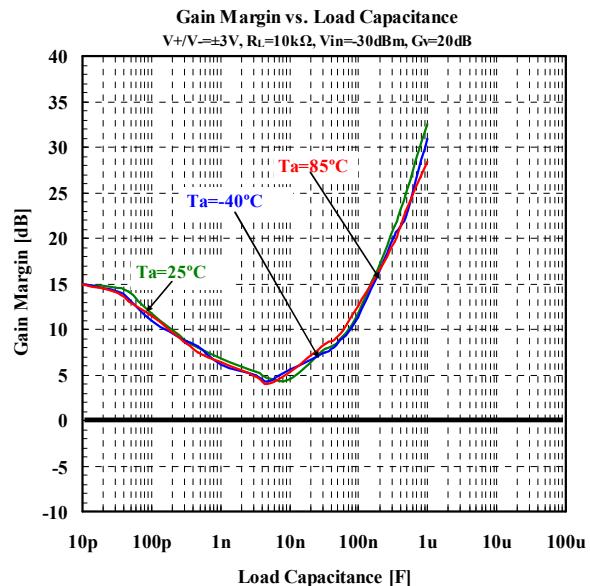
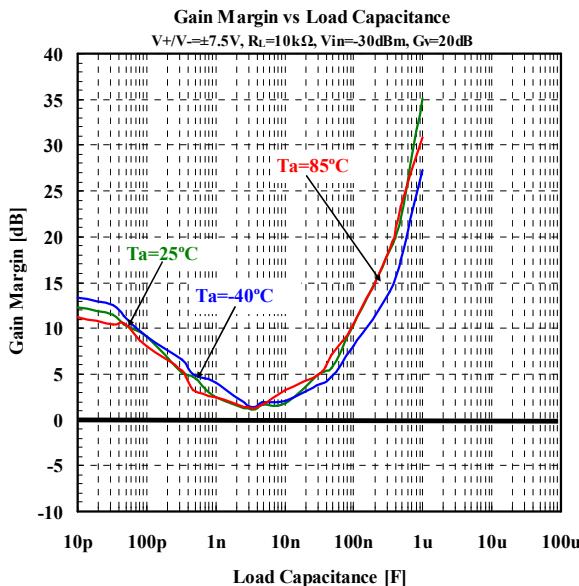
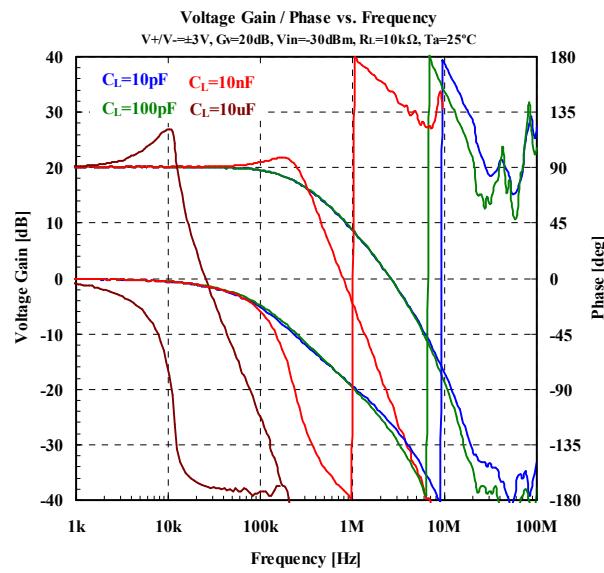
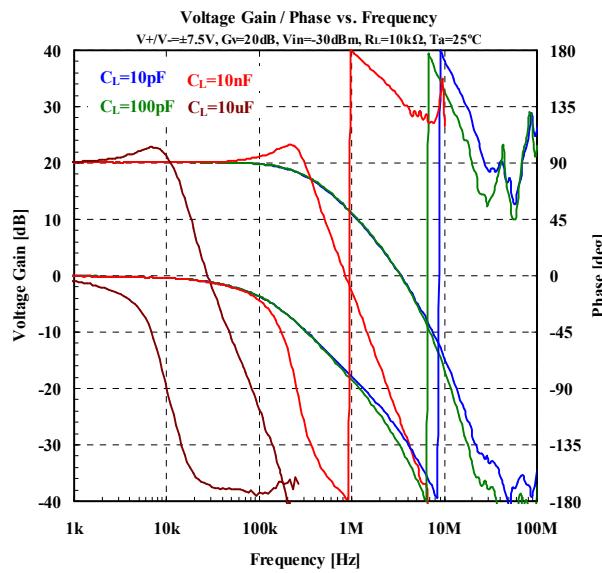


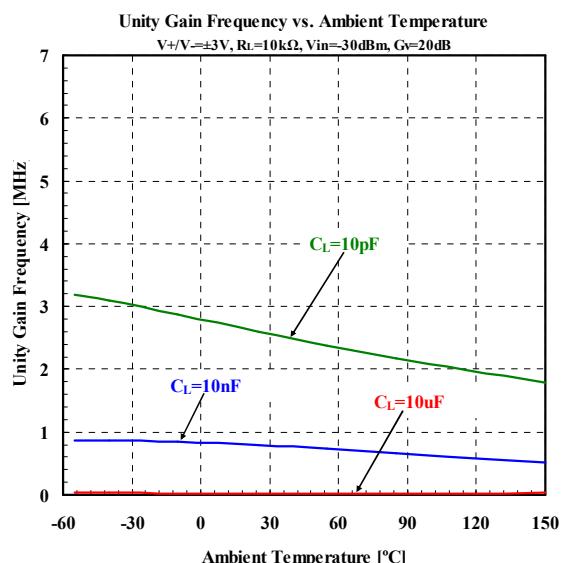
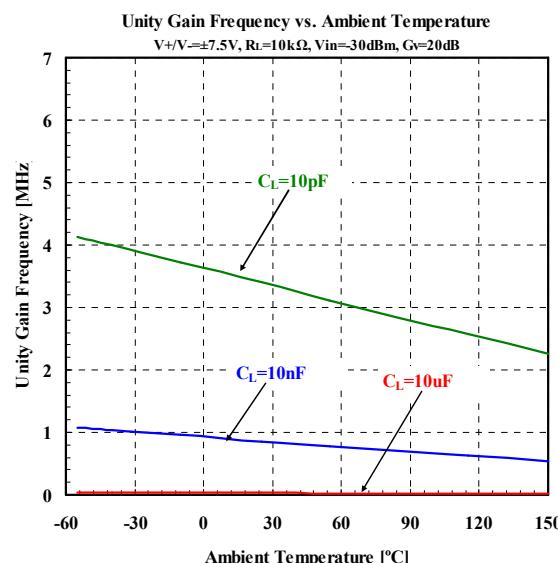
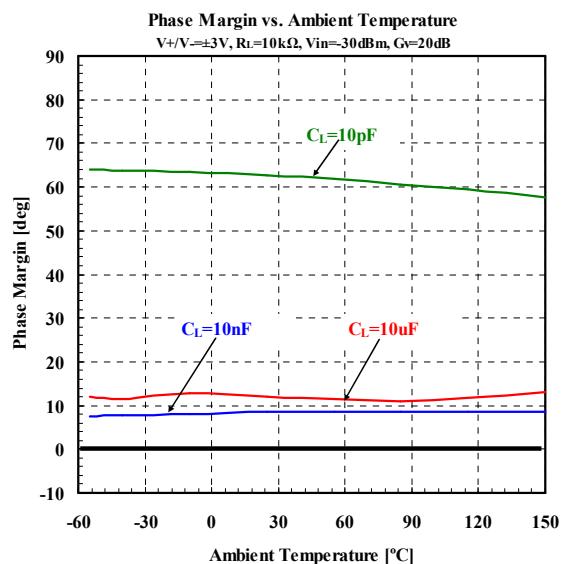
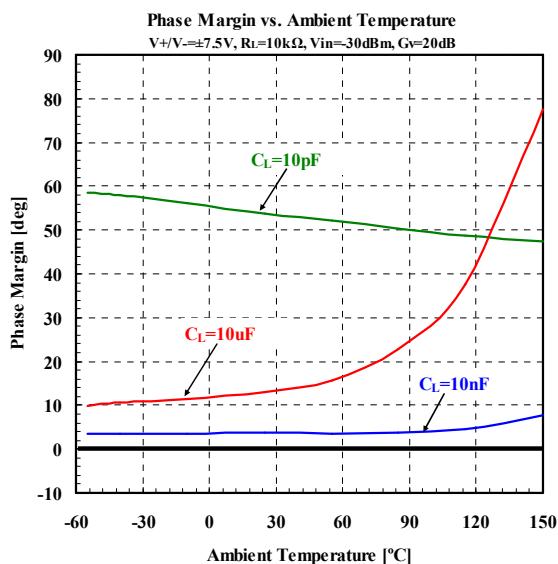
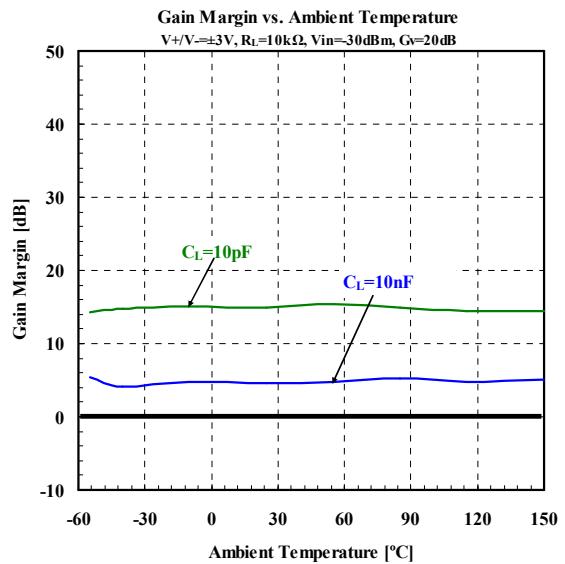
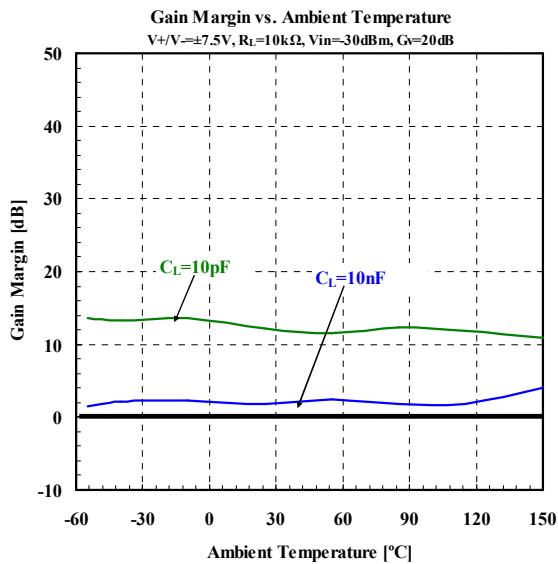


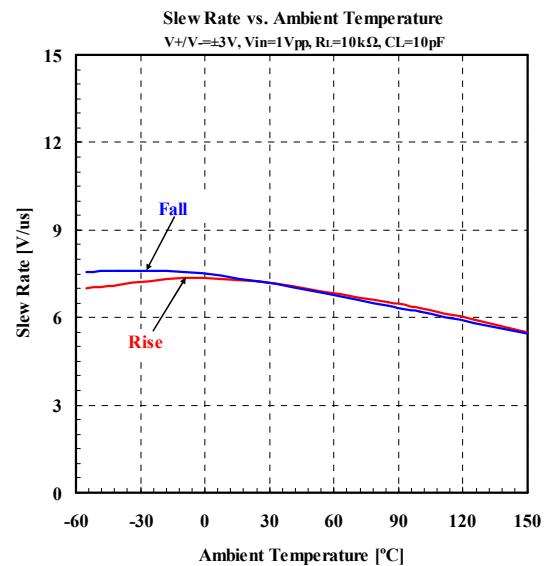
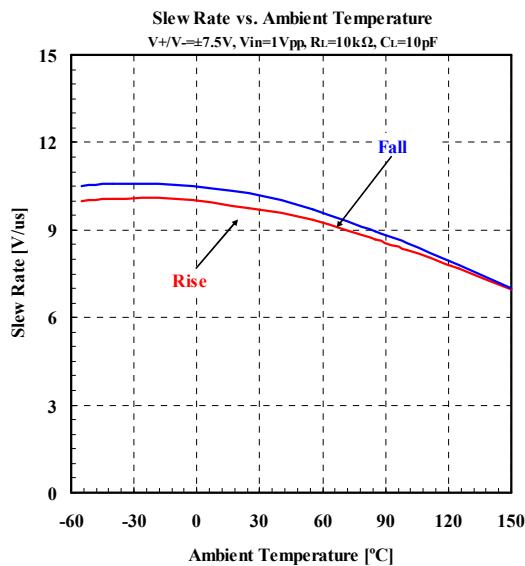
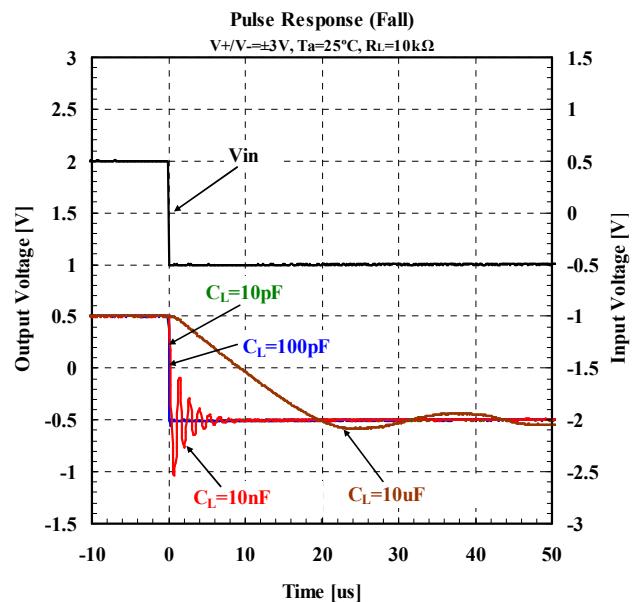
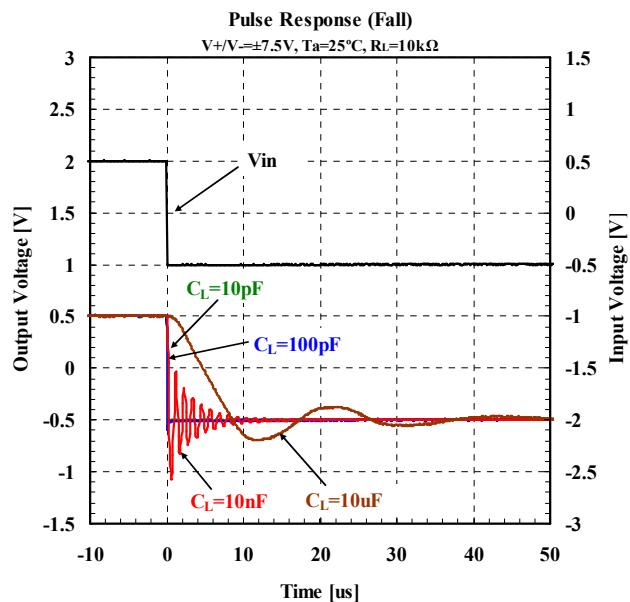
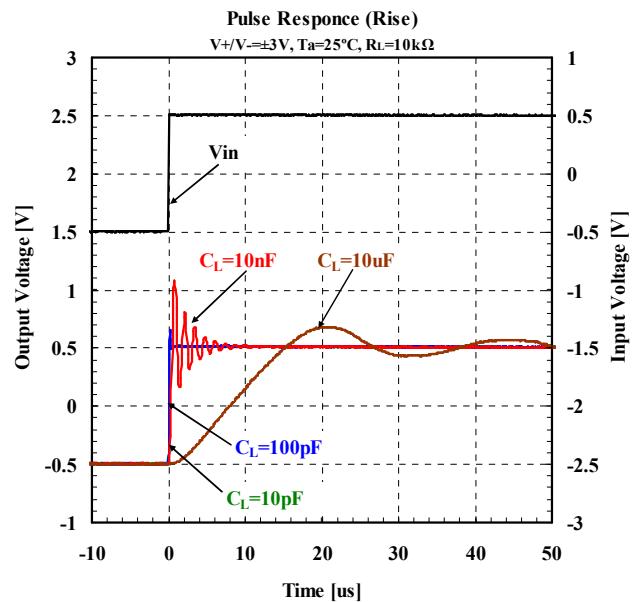
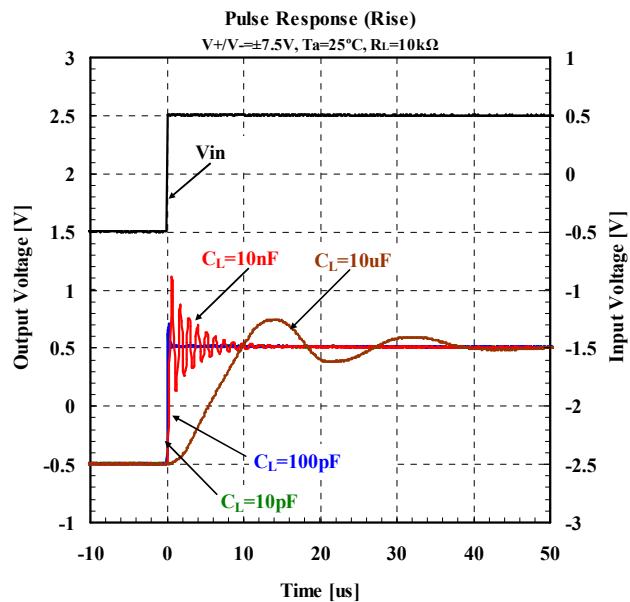


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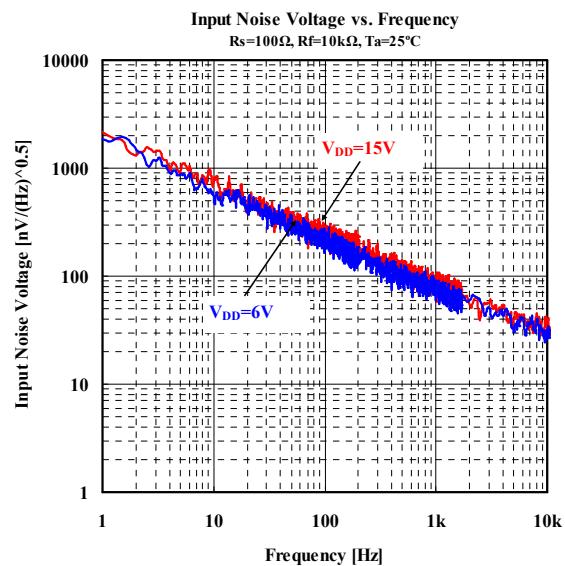
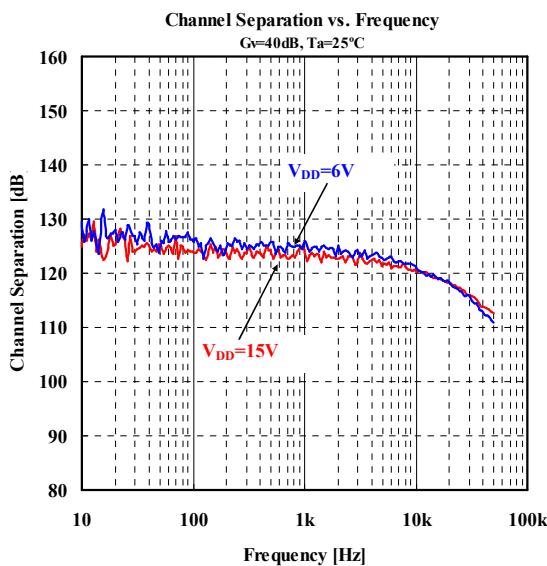
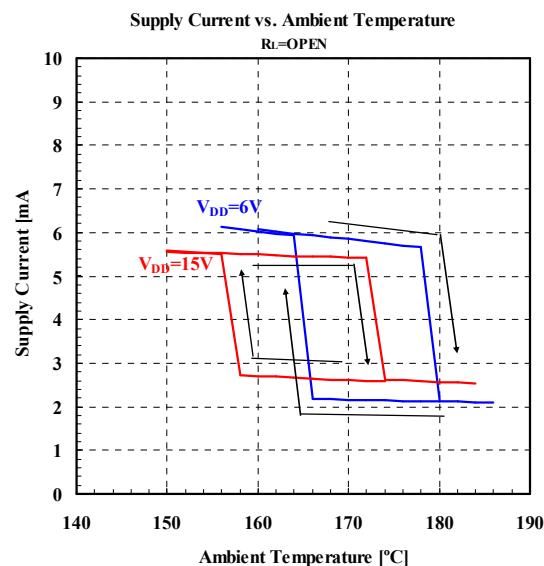
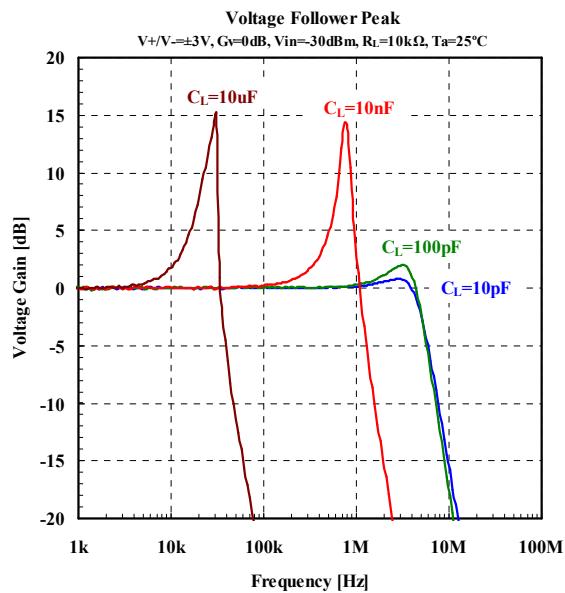
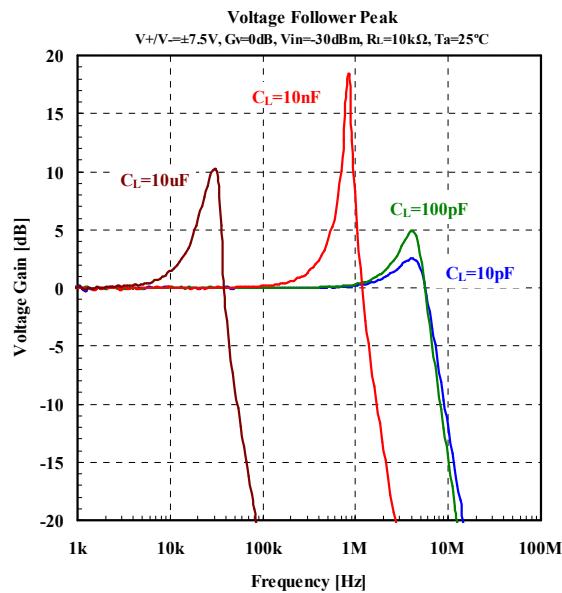


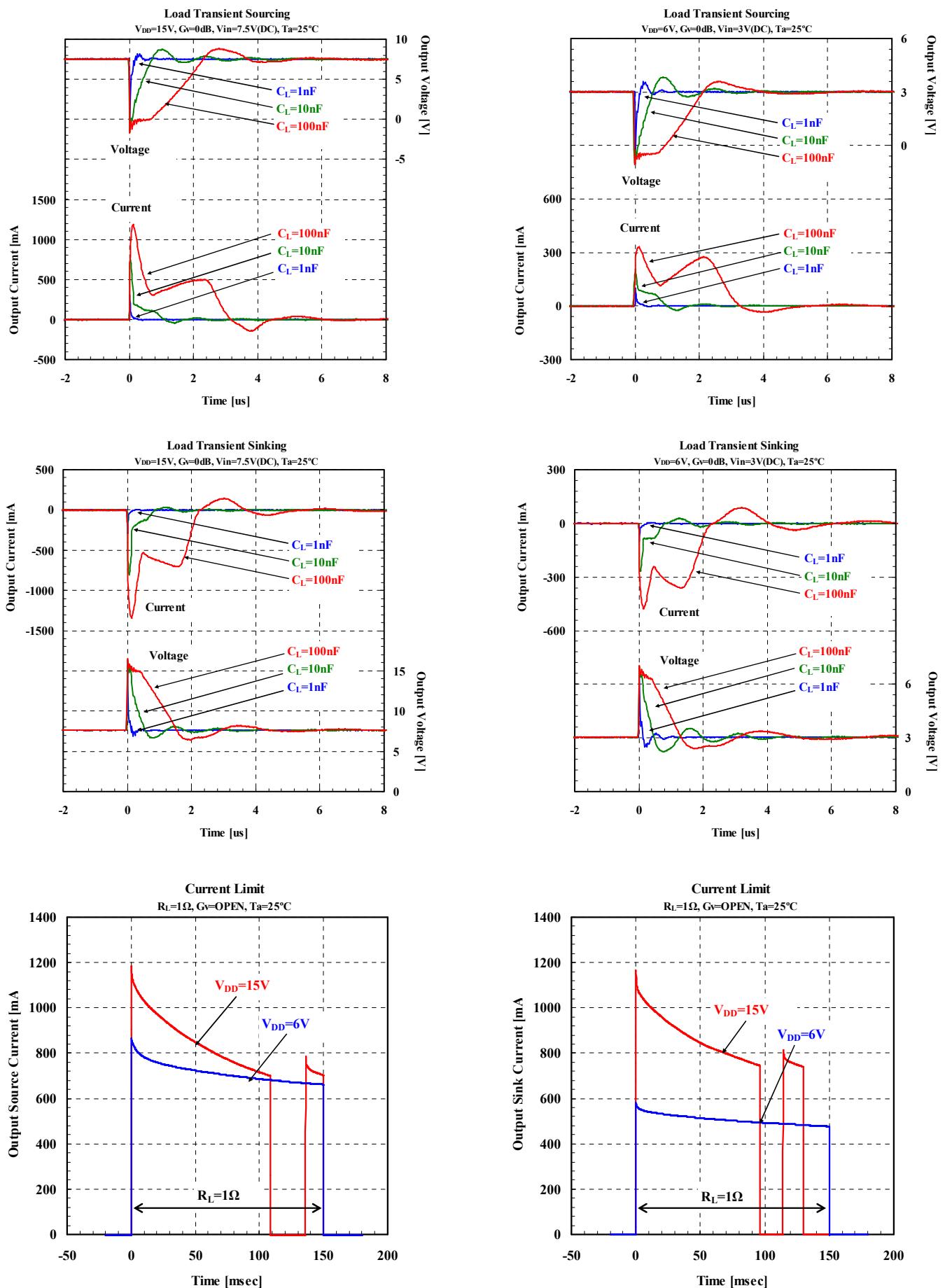


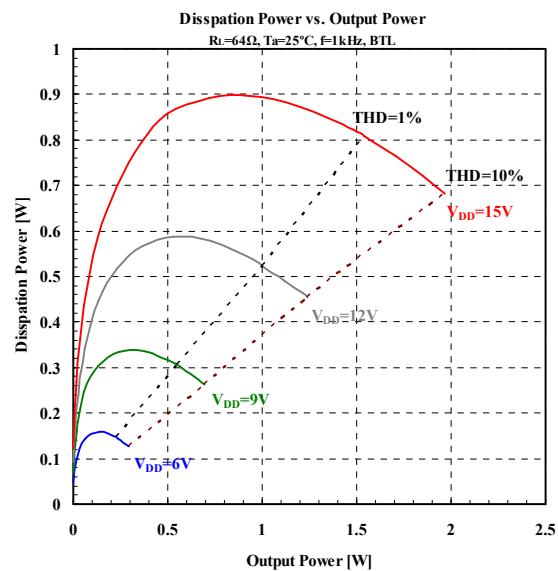
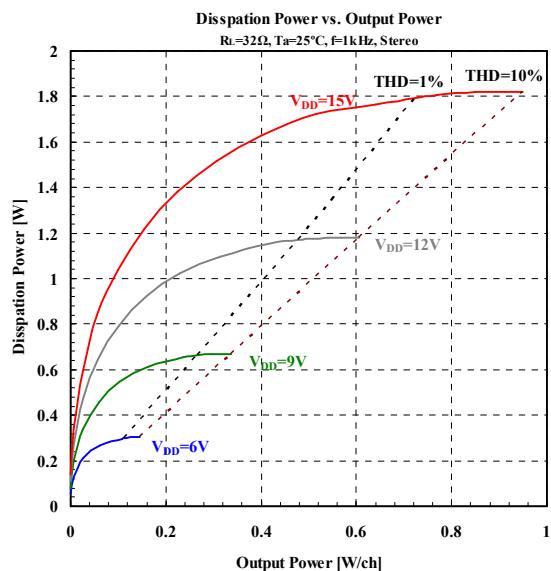
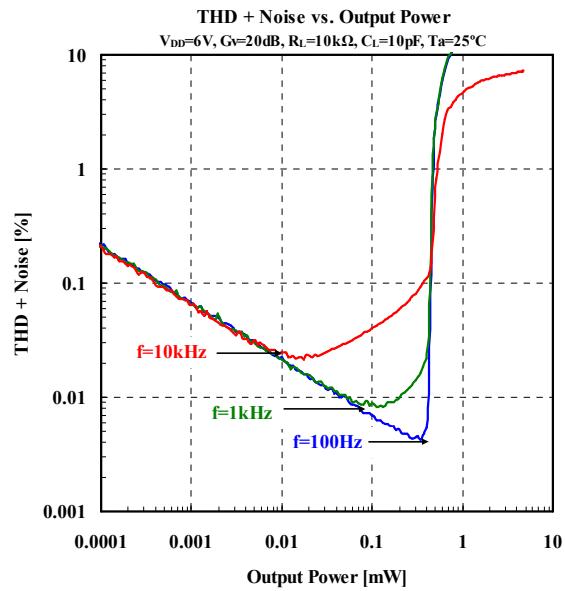
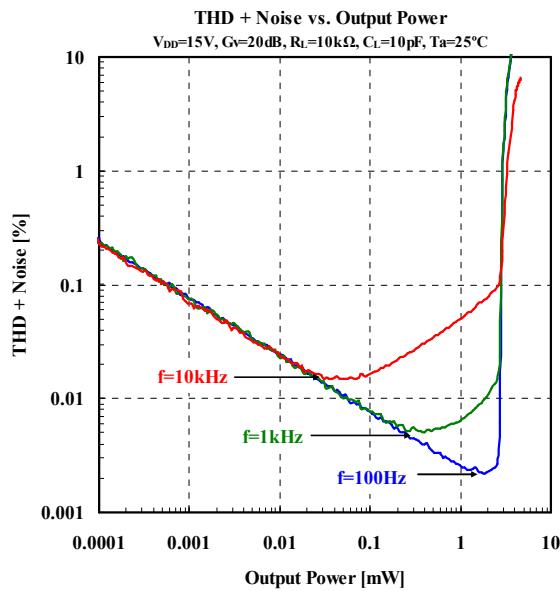




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[CAUTION]

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